WinWay

TWSE 6515

Investor Presentation

● ● ● ● ● 2025.05.19

RESTRICTED SECURITY C

Safe Harbor Notice

This presentation may contain forward-looking statements. All statements, other than statements of historical facts, that address activities, events or developments that WinWay Technology Co., Ltd. expects or anticipates will or may occur in the future (including but not limited to projections, targets, estimates and business plans) are forward-looking statements.

WinWay's actual results or developments may differ materially from those indicated by these forward-looking statements as a result of various factors and uncertainties, including but not limited to market demand, price fluctuations, competition, change in legal, government policies, financial market conditions, and other risks and factors beyond our control.

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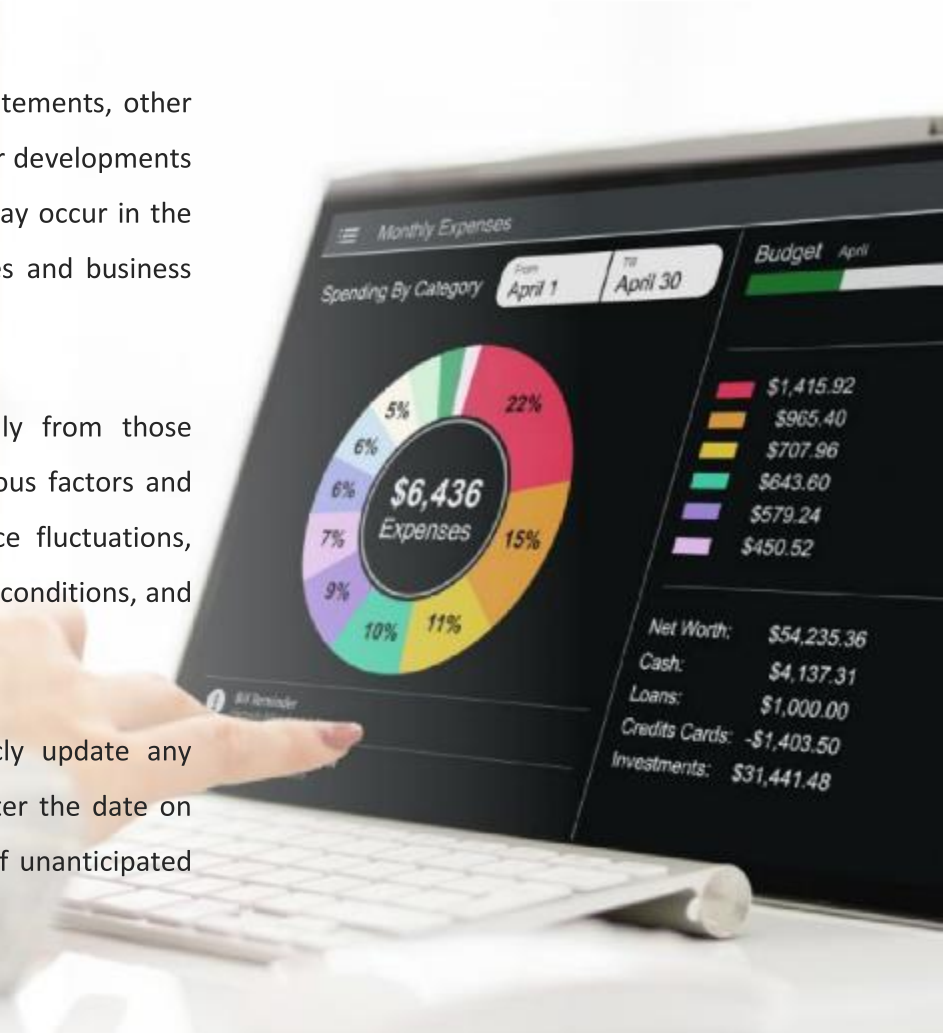

Company Information

- **Founded**

  2001 / 4 / 10

- **Business Operation**

  Design, manufacture, sale and service of test interface products

- **Chairman & CEO**

  Mark Wang

- **Capital Stock**

  NTD 358,603,260

- **Employees**

  986

- **Registered Address**

  No.68, Chuangyi S. Rd, Nanzi Dist.
  Kaohsiung City, Taiwan

Kaohsiung Headquarter

Hsinchu
Branch Office

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Company Vision

Innovation

We deliver the best possible test tooling solutions to our customers through technological innovation.

Quality

We exceed customers' quality requirements by offering cost-effective total solutions and on-time delivery worldwide.

Service

We strive to become the world's leading professional testing service provider in all phases of IC testing.

Agenda

Global Presence

Industry Trend

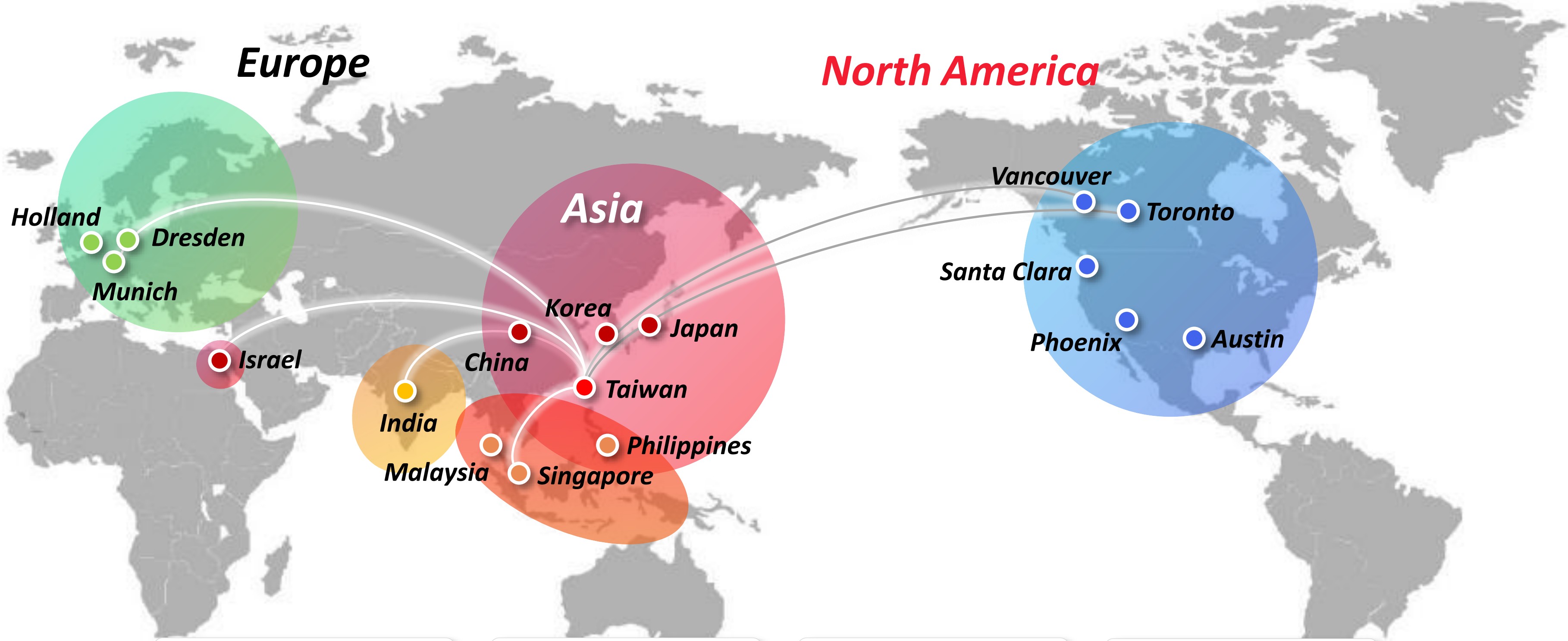
Financial Performance

R&D Innovation

01

Global Presence

Global Service & Support Network



KH Spring Probe

Spring Probe
for Socket

KH Plant

Coaxial Socket
HyperSocket™

Hsinchu Plant

Vertical Probe Card
MEMS Probe Card

Suzhou Plant

Burn-in Socket

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Semiconductor Test Interface Leadership

1

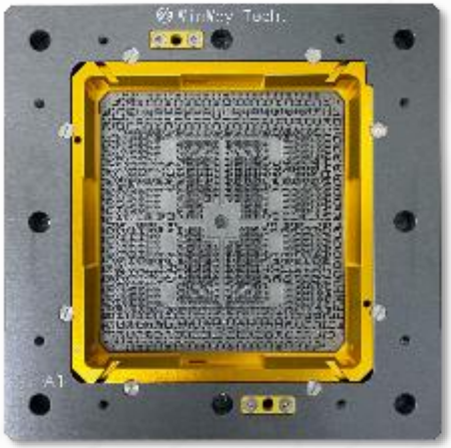
2024
Test Socket Ranking

2

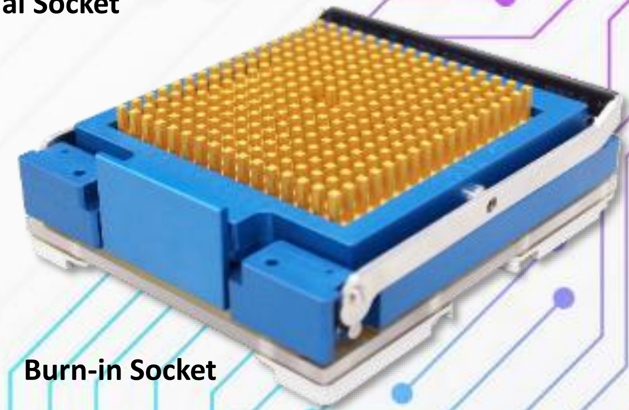
2024
Test and Burn-in Socket Ranking

18

2024
Probe Card Ranking



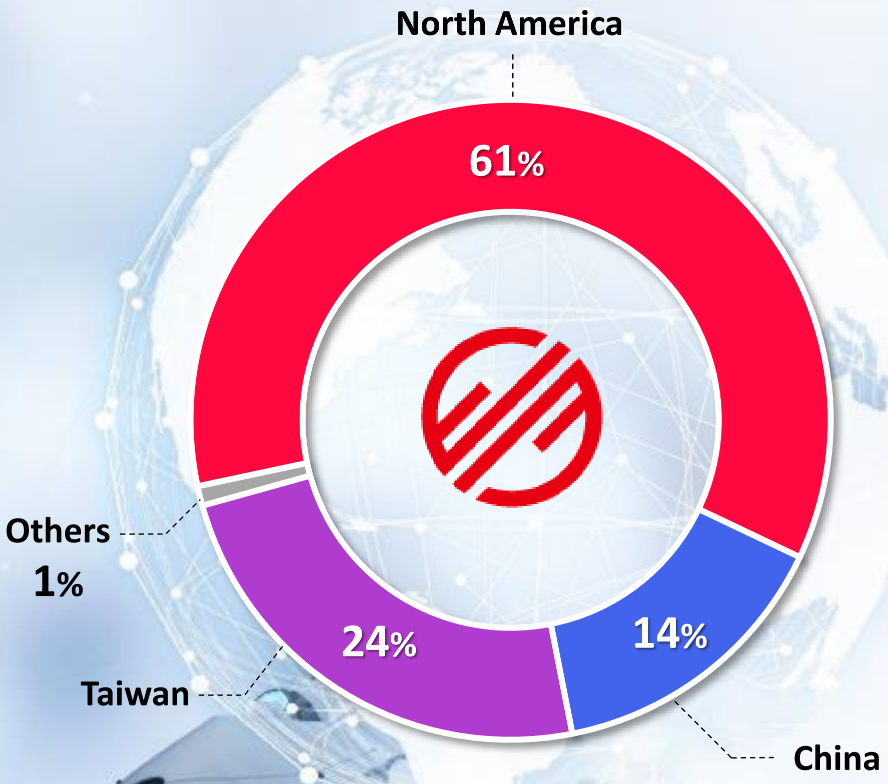
Coaxial Socket



Burn-in Socket

SOURCE：Yole Intelligence, 2025/04

Worldwide Customer



86% Top10 Customers

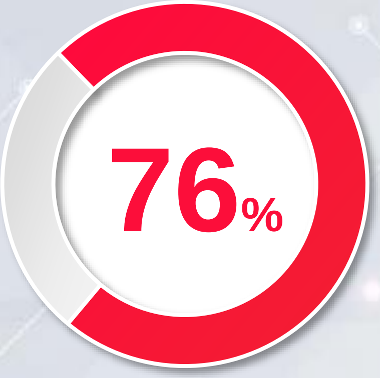
- AI
- AP
- HPC
- CPU
- ASIC
- GPU

200^{+} Active Customers

- IC Design
- IDM
- CSP
- OSAT
- Foundry

Bolstered by Advanced Technology

(Year 2024)



Advanced Node

AI

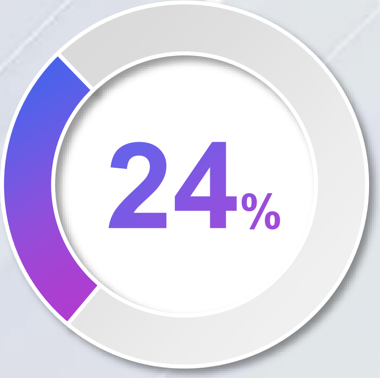
HPC

GPU

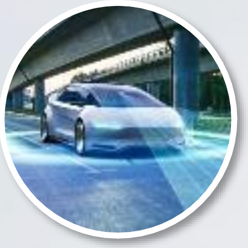
CPU

Smart Phone

7nm (or equivalent node) and below



Mature Node



Automotive

Networking

IoT

DTV & STB

NAND Flash

02

Industry Trend

AI Semiconductor Mega-Trend

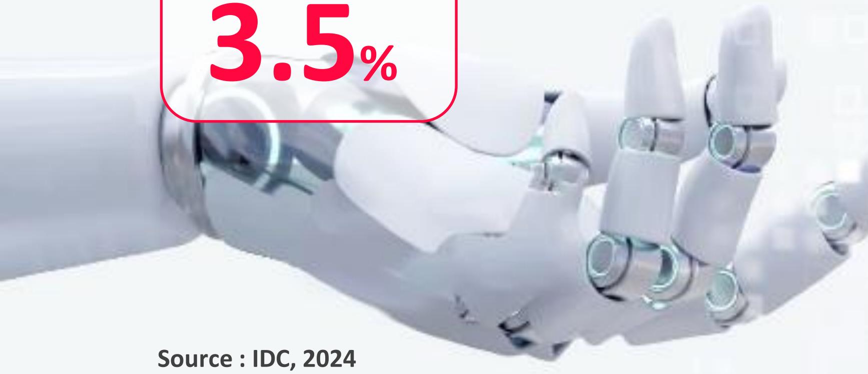
Global AI Economic Impact

$19.9

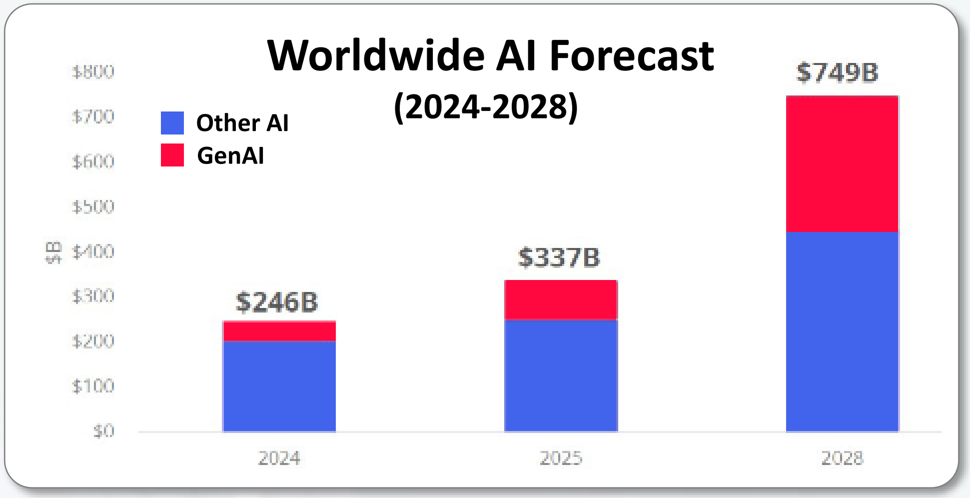
Trillion by 2030

Global GDP

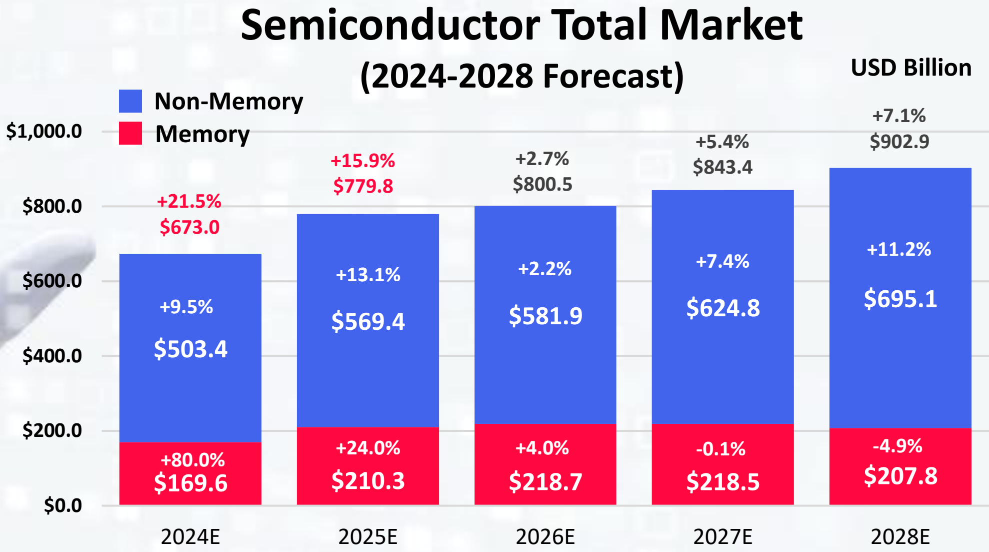
3.5%



Source : IDC, 2024



Worldwide AI Forecast
(2024-2028)



Semiconductor Total Market
(2024-2028 Forecast)

USD Billion

Driving Force for AI

AI Server

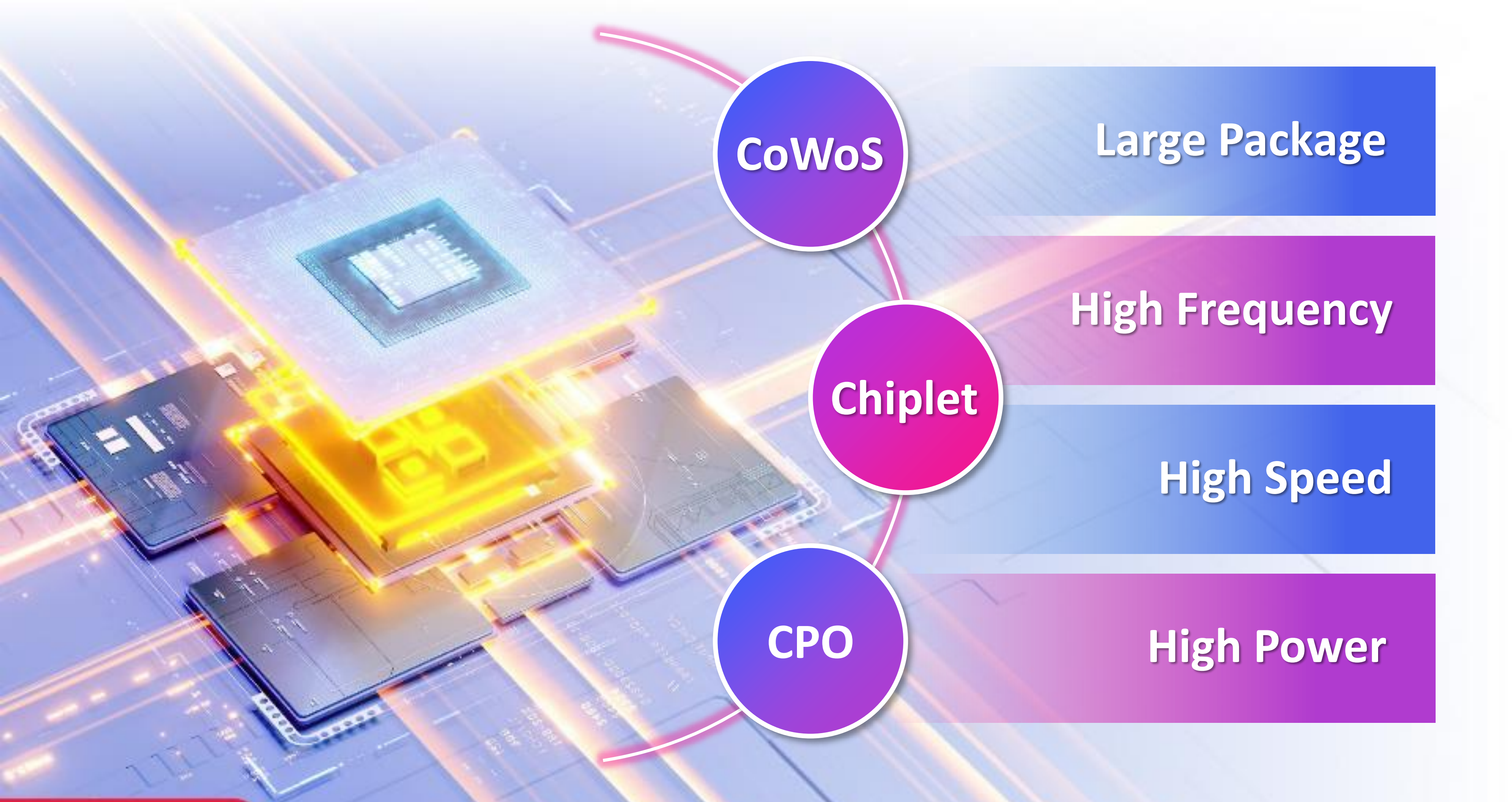
Data Center

AI PC & Phone
Edge Computing

5G&6G Low Earth Orbit Satellite

High Speed
Networking

High Performance Testing Driven by Advanced Packaging



CoWoS

Chiplet

CPO

Large Package

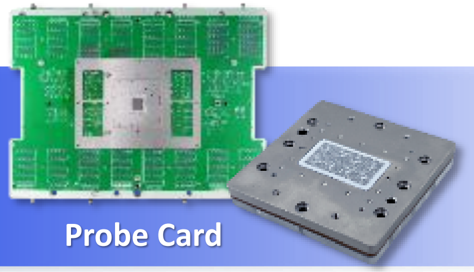
High Frequency

High Speed

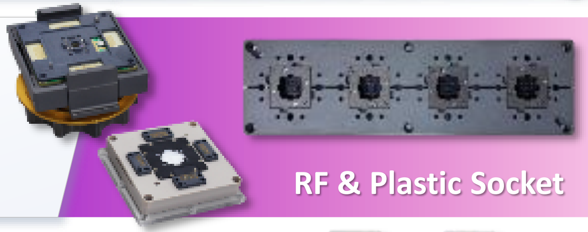
High Power

Total Solution for Semiconductor Test

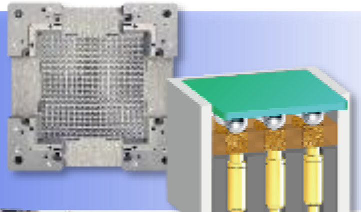
Wafer Sort
(CP - Circuit Probe)


Probe Card

Final Test
(Final Test)


RF & Plastic Socket

SLT (System Level Test)
SFT


Coaxial Socket & HyperSocket™

Functional Burn-in


Burn-in Socket

DFT Design For Testing DFM Design For Manufacturing

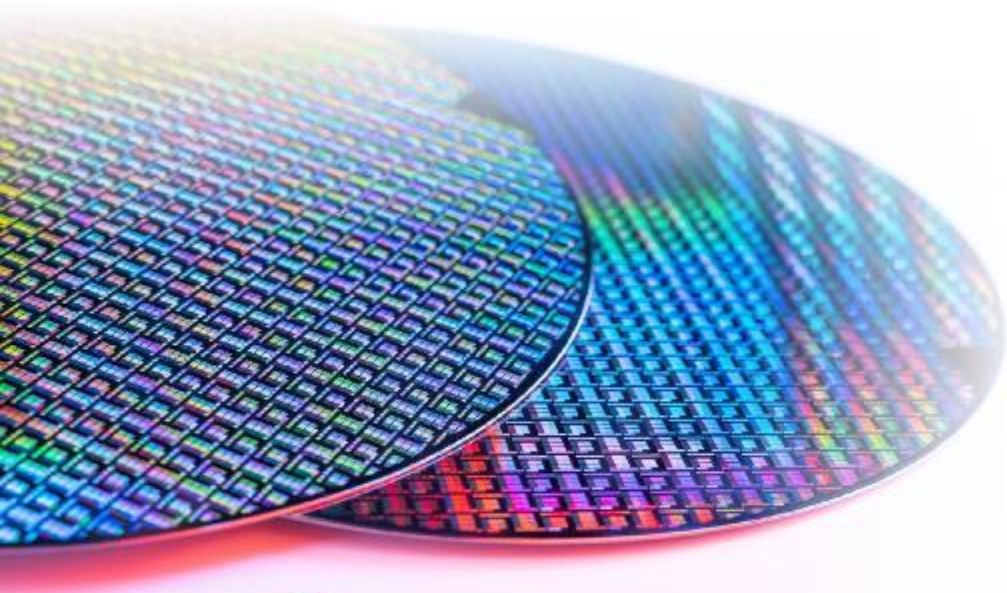
Greater Importance on Chip Probing

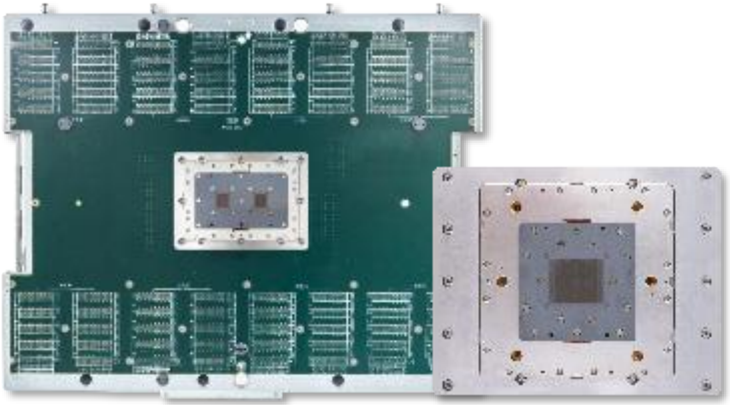
From Shadows to Spotlight

K.G.D

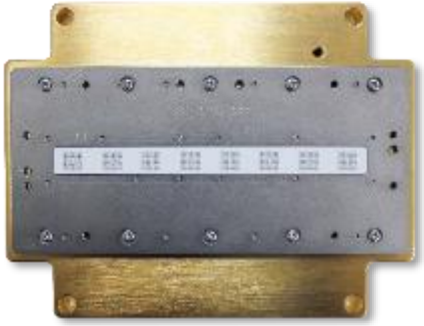
Close to
Known **G**ood **D**ie

- CoWoS
- Chiplet
- CPO





MEMS VPC



WLCSP Probe Card

Cobra VPC

Advanced Packaging Accelerates Demand for System Level Testing

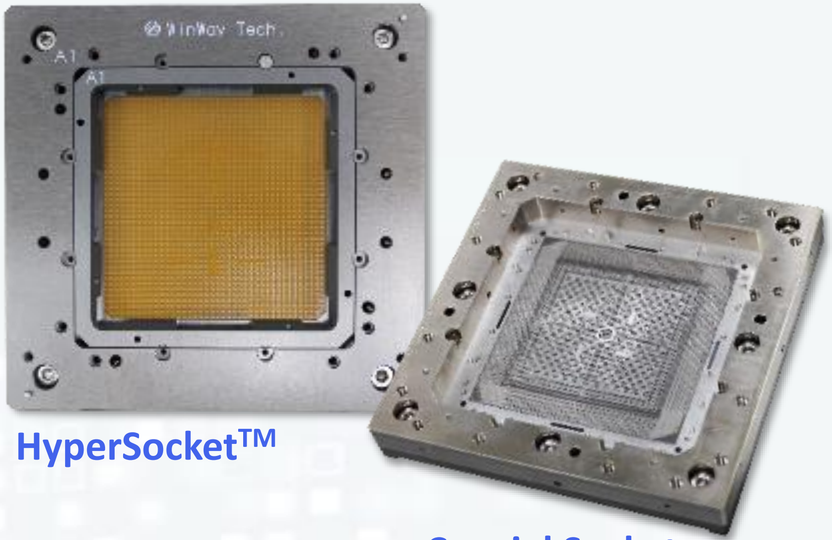
SLT&SFT

2024-2029 CAGR

More than **15%** ↑

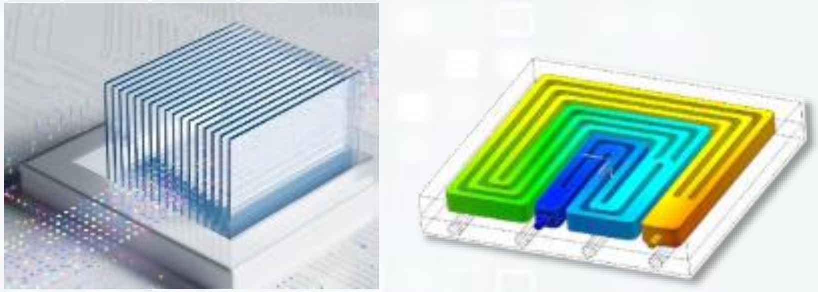
Greater than industry growth

Source : WinWay 2024



HyperSocket™

Coaxial Socket

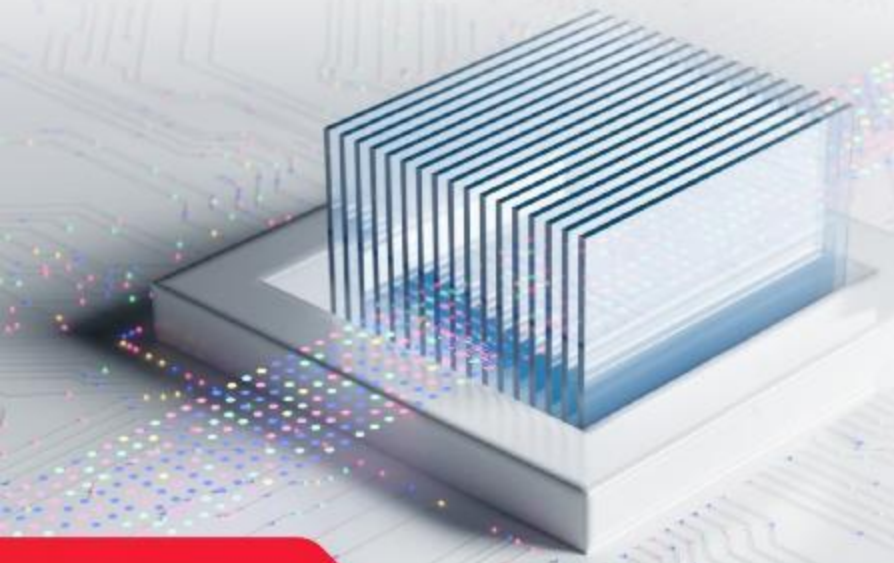


Thermal System (Liquid Cooling)

Future Trend for High-Speed Burn-in

Functional Burn-in

- High Power Burn-In Oven
- System Level Test Burn-In



High Power 1000W

Large Package 120 X 120 mm^2

High Speed PCIE Gen5 32Gbps

Collaborative Robot

Automotive

Data Center

03

Financial Performance

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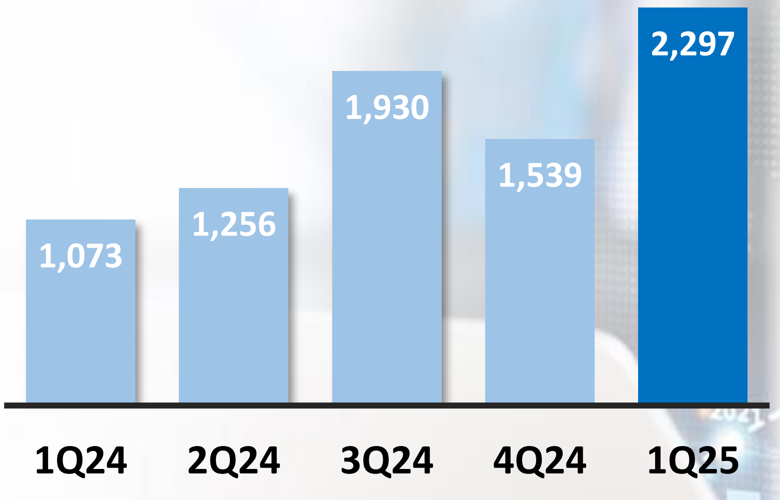
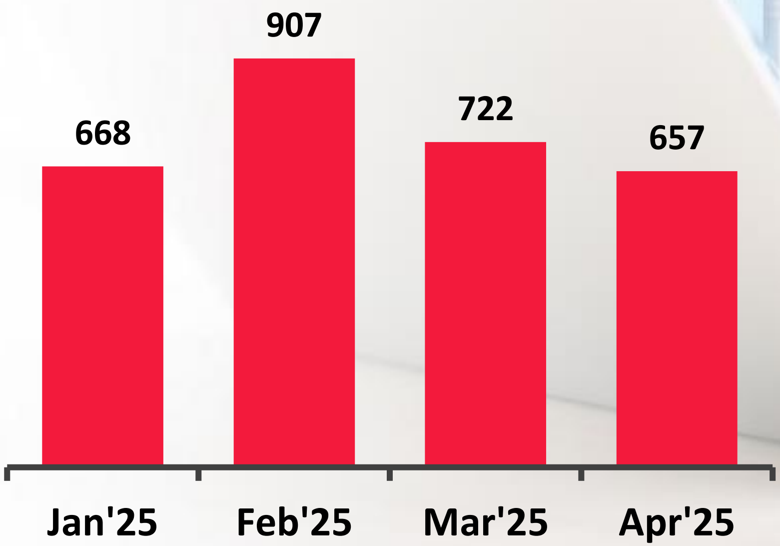
Revenue Trend

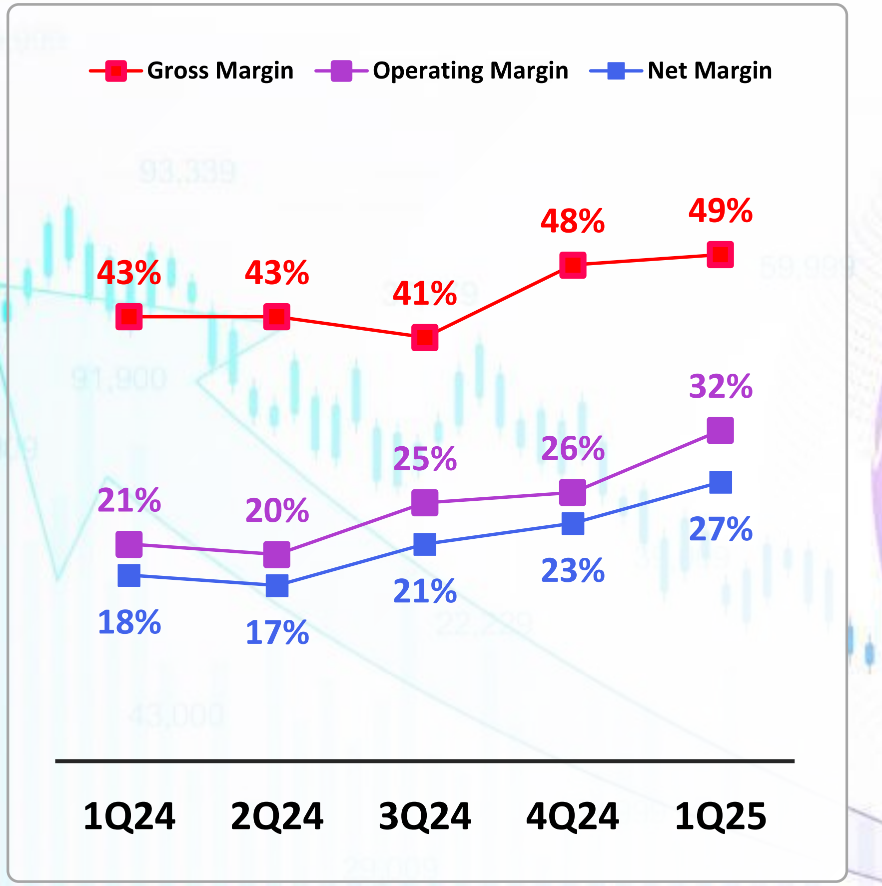
QUARTERLY REVENUE
(NTD MILLION)



MONTHLY REVENUE
(NTD MILLION)



Profitability Trend



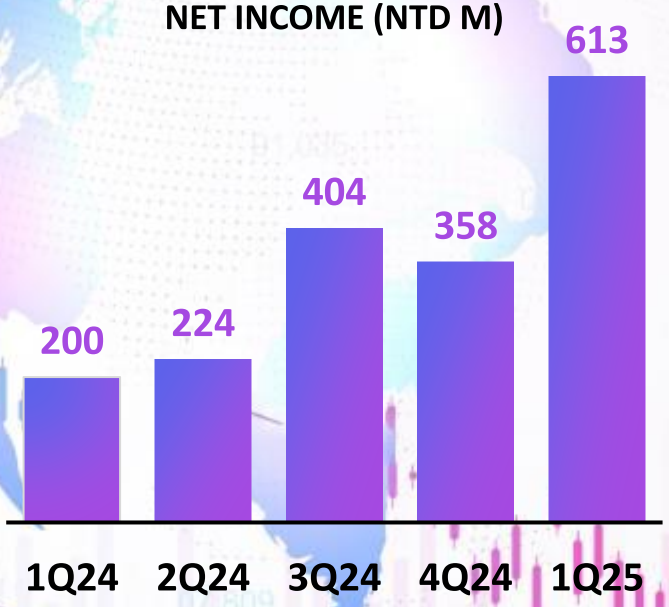
2024 EPS

34.31

Dividend

25.0

EPS (NT$)	5.81	6.52	11.75	10.23	17.21



Revenue by Product Mix

(1Q 2025)

🟥	Coaxial Socket	41%
🟪	RF & Plastic Socket	8%
🟩	Contact Element	8%
🟧	Probe Card	36%
🟦	Burn-in Socket	3%
⬜	Others	4%

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Revenue by End Market

END MARKET (1Q 2025)

HPC & AI

49% ↗

HyperSocket™ , Coaxial

PC & Gaming

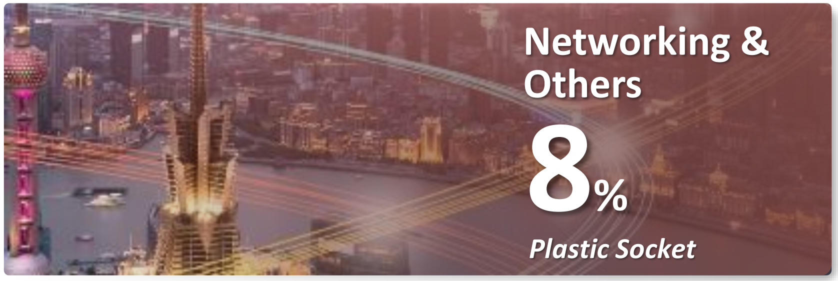
37% ↗

HyperSocket™ , Coaxial

Smart Phone

6%

POP Plastic Socket



Networking & Others

8%

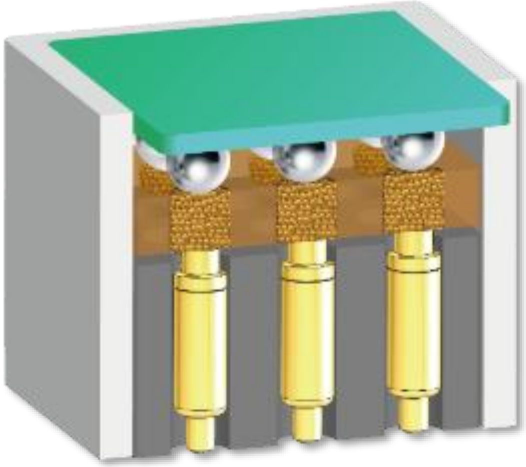
Plastic Socket

04

R&D Innovation

Best-in-Class Test Socket

WinWay HyperSocket^{TM}



- Best solution for high-speed signal
- Well-positioned for larger, more advanced package design
- Superior thermal dissipation for high-current testing

Patent NO.

- TWI862047
- TWI862191
- CN20570508U

Patent Pending

- USA
- Japan
- Korea
- Malaysia

AI&HPC

Smartphone

Automotive

SLT

SFT

Co-Packaged Optics Test Solution

Total Solution for CPO

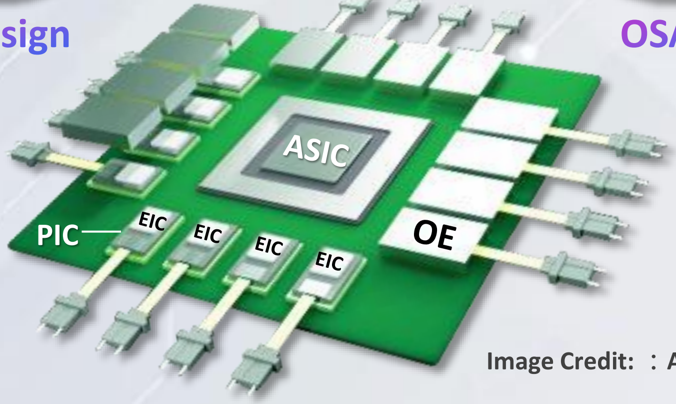
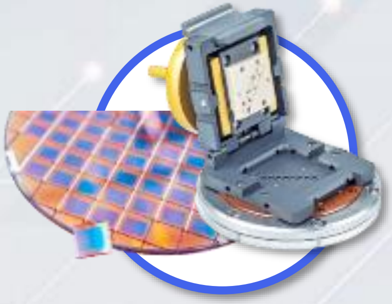
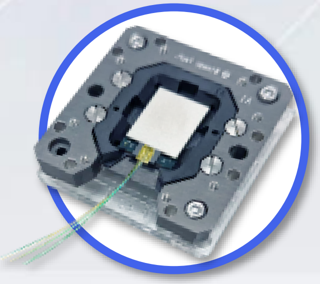


Image Credit: ：ASE

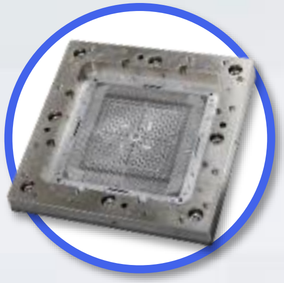
Co-Packaged Optics



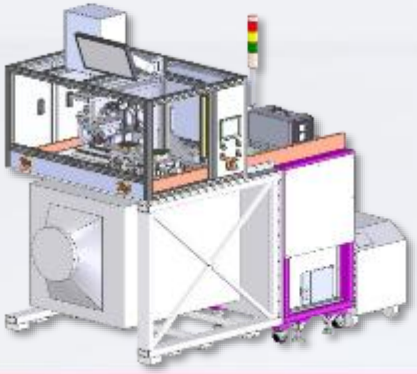
WLCSP Fine Pitch Socket



Optical and Electrical Test Socket



Coaxial Socket



Double Sided Probing System

Spring Probe Manufacturing

Socket All in House

Cost Reduction **Customer Growth**

2025 Demand **8M / Month**

2025 Capacity **4.5M / Month**

SEMICON SEA

2025.05.20-22

Singapore / Sands Expo and Convention Centre

SWTEST

2025.06.02-04

USA / Omni La Costa Carlsbad, CA

SHAREHOLDERS’ MEETING

2025.06.19

Taiwan / Zhuang Jing Auditorium, Kaohsiung

TWSE: 6515

Q&A

WinWay 股票代號 6515

THANK YOU

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